ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES*	Material Composit © Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declarat	ion of the succession of the s	ubstances v s all lower	within the manufactu level materials for v	rer listed i which the n	tem. Note: nanufactur	if the item is an as er has engineering	ssembly with low responsibility.	
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
upplier Informa	tion														
Company name*			Company unique ID				Unique ID Authority				Respons	Response Date*			
onsemi											2024-05-17				
Contact Name			Title - Contact				Phone - Contact*				Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester 1	Requester Item Number Mfr Ite		m Number Mfr Item Name				Effective Date	Pe Date Version Manufacturing Site			Weight*	UOM	Unit Type		
		NSBC11	NSBC114EDXV6T5G SS SOT563 RST		X XSTR TR 2'		2024-05-17	2024-05-17 CN1		CN1		2.72	mg	Each	
Ianufacturing P	roccess Information	1													
Terminal Plating / Grid Array Material Terminal			erminal Base A	ase Alloy J-STD-020 MSL Rating			Peak Process Body Temperature Max Time at Peak				Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU Al			U Alloy	oy 1			260 C 30		seconds 3						
omments															
vel 1 - maximum tim	e at peak temperature d	luring sol	dering is 10-3	0 seconds											
or more information	regarding material com	position	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.												
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless	otherwise noted).							
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.06	mg	Supplier	Silicon (Si)	7440-21-3		0.06	mg
Lead Frame	1.18	mg	Supplier	Silver (Ag)	7440-22-4		0.21	mg
			В	Nickel (Ni)	7440-02-0		0.3646	mg
			Supplier	Iron (Fe)	7439-89-6		0.5039	mg
			Supplier	Copper (Cu)	7440-50-8		0.1015	mg
Mold Compound-Black	1.4	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.14	mg
			Supplier	Carbon Black (C)	1333-86-4		0.007	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.203	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.91	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.14	mg
Plating	0.06	mg	Supplier	Tin (Sn)	7440-31-5		0.06	mg
Wire Bond - Cu	0.02	mg	Supplier	Copper (Cu)	7440-50-8		0.02	mg